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CELCON® M25

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Celcon® acetal copolymer grade M25 is a high molecular weight, higher toughness and impact resistance grade primarily used for extrusion and selected injection molding applications.
Chemical abbreviation according to ISO 1043-1: POM
Please also see Hostaform® C 2521.

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	2.2	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.2	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2460	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	62	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	13	%	ISO 527-1/-2
Flexural modulus	2430	MPa	ISO 178
Flexural stress at 3.5%	68	MPa	ISO 178
Flexural strain at failure	3.5	%	ISO 178
Compressive stress at 1% strain	31	MPa	ISO 604
Tensile creep modulus, 1h	2100	MPa	ISO 899-1
Tensile creep modulus, 1000h	1100	MPa	ISO 899-1
Charpy impact strength, 23°C	250[P]	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	190	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	9.1	kJ/m^2	ISO 179/1eA
Izod notched impact strength, 23°C	8.3	kJ/m^2	ISO 180/1A
Izod notched impact strength, -30°C	6.0	kJ/m^2	ISO 180/1A
Izod impact strength, 23°C	133	kJ/m^2	ISO 180/1U
Izod impact strength, -40°C	6.41	kJ/m^2	ISO 180/1U
Hardness, Rockwell, M-scale	82		ISO 2039-2
Poisson's ratio	0.38[C]		

[P]: Partial Break

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	94	°C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	150	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	120	E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2

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Specific heat capacity of melt	2210	J/(kg K)	ISO 22007-4

Flammability

Oxygen index	14.9	%	ISO 4589-1/-2

Electrical properties

Surface resistivity	1.3E16	Ohm	IEC 62631-3-2
Arc Resistance	240	s	UL 746B

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.75	%	Sim. to ISO 62
Water absorption, Immersion 24h	0.2	%	Sim. to ISO 62
Density	1410	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	185	°C
Min. melt temperature	180	°C
Max. melt temperature	190	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	130	°C

Characteristics

Processing	Injection Moulding, Film Extrusion, Extrusion, Sheet Extrusion, Other Extrusion, Blow Moulding, Calendering, Compression moulding
Delivery form	Pellets
Additives	Release agent

Additional information

Injection molding

Preprocessing

Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required.

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Maximum water content = 0.35%

Processing

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.

Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

Postprocessing

Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

Film extrusion

Preprocessing

Drying is generally not required because Celcon materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can cause surface defects on the extruded film. For better uniformity especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 3 Hrs. at 80 C (180 F). Desiccant hopper dryers are not required. Max. moisture content = 0.35%.

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio of at least 3:1 and preferably 4:1 to assure good melting and melt homogeneity. The design should be approximately 35% each for feed and metering sections with the remaining 30% as the transition zone.

Melt temperature: 160-220 C (320-430 F)

Postprocessing

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Postprocessing conditioning or moisturizing is not required.

Other extrusion

Preprocessing

Drying is generally not required because Celcon materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can cause surface defects. For better uniformity especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying is 3 hours at 80 C (180 F). Desiccant hopper dryers are not required. Max. moisture content = 0.35%

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio of at least 3:1 and preferably 4:1 to assure good melting and uniform melt homogeneity. The design should be approximately 35% each for the feed and metering sections with the remaining 30% as transition zone.

Melt temperature 180-220 C (355-430F)

Postprocessing

Postprocessing conditioning or moisturizing are not required. For thick walled sections (>3mm or 1/8 in.), annealing is recommended to reduce internal stresses.

Annealing temperature: 130-140 C (265-285 F)

Annealing time: 10 min/mm thickness

Profile extrusion

Preprocessing

Drying is generally not required because Celcon materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can cause surface defects on the extrusion. For better uniformity especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 3 Hrs. at 80 C (180 F). Desiccant hopper dryers are not required. Max. moisture content = 0.035%.

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio of at least 3:1 and preferably 4:1 to assure good melting and melt homogeneity. The design should be approximately 35% each for feed and metering sections with the remaining 30% as the transition zone.

Melt temperature: 180-220 C (360-430 F).

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Postprocessing

Postprocessing or moisturizing is not required. For thick walled extrusions (>3 mm or 1/8 in.), annealing is recommended to reduce internal stresses.

Annealing temperature: 130-140 C (265-285 F)
Annealing time: 10 min/mm thickness

Sheet extrusion

Preprocessing

Drying is generally not required because Celcon materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to surface defects. For better uniformity in sheet extrusion especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying is 3 hours at 80 C (180 F). Desiccant hopper dryers are not required. Max. water content = 0.35%.

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio (at least 3:1 and preferably 4:1) to assure good melting and uniform melt homogeneity. The screw design should be approximately 35% each for the feed and metering sections with the remaining 30% as the transition zone.

Melt temperature 180-190 C (355-375 F).

Postprocessing

Postprocessing conditioning or moisturizing is not required. For thick walled sections (>3mm or 1/8 in.), annealing is recommended to reduce internal stresses.

Annealing temperature: 130-140 C (265-285 F)

Annealing time: 10 min/mm wall thickness

Blow molding

Preprocessing

Consult product information services.

Processing

Consult product information services.

Postprocessing

Consult product information services.

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Calandering

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Preprocessing

Consult product information services.

Processing

Consult product information services.

Postprocessing

Consult product information services.

Compression molding

Preprocessing

Consult product information services.

Processing

Consult product information services.

Postprocessing

Consult product information services.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Continental	TST N 055 54.07	
Ford	WSK-M4D635-A1	Natural & Black
General Motors	GMW22P-POM-C1	Black
Li Auto	Q/LiA5310020	2021 (V2)
Nissan	POM-IC1-1	
Stellantis - Chrysler	MS.50095 / CPN-1986	Black
Stellantis - Chrysler	MS.50095 / CPN-4240	Natural

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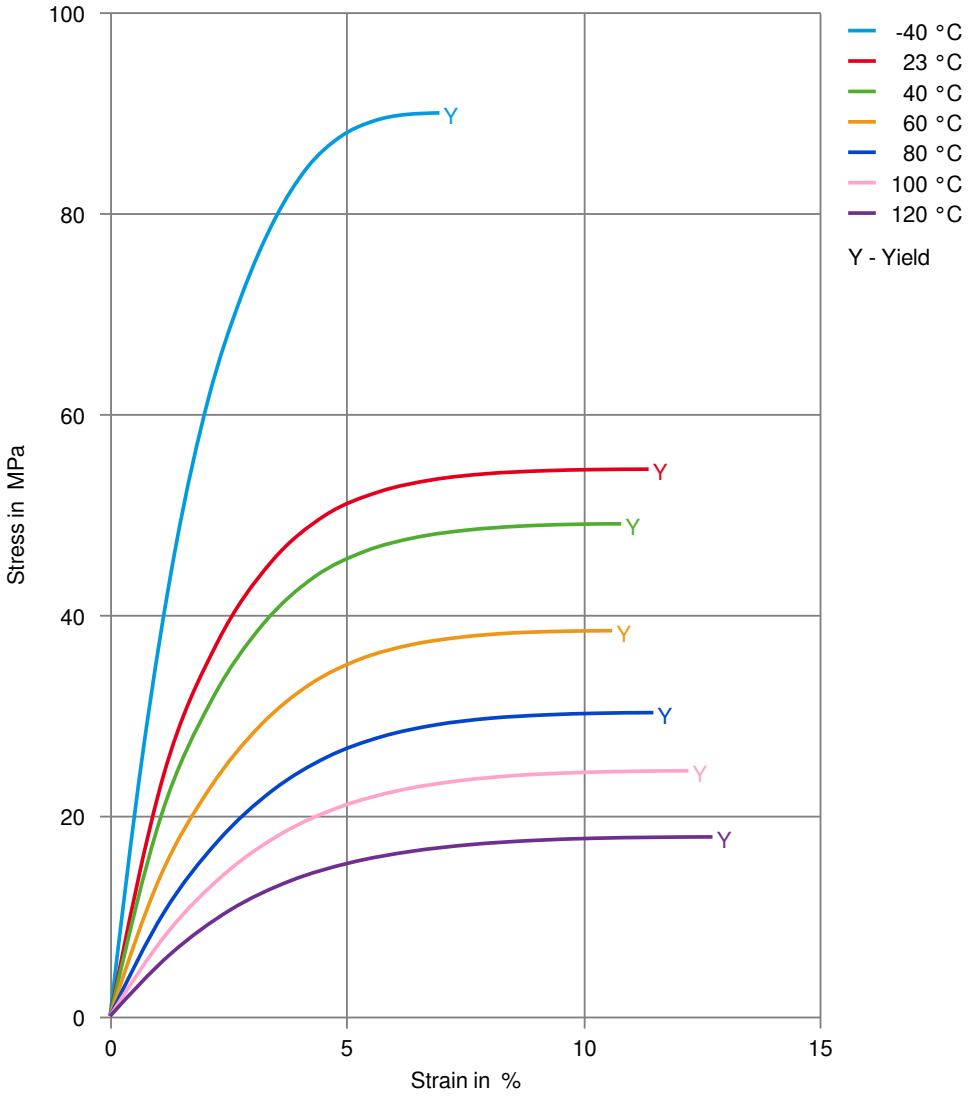
Stress-strain



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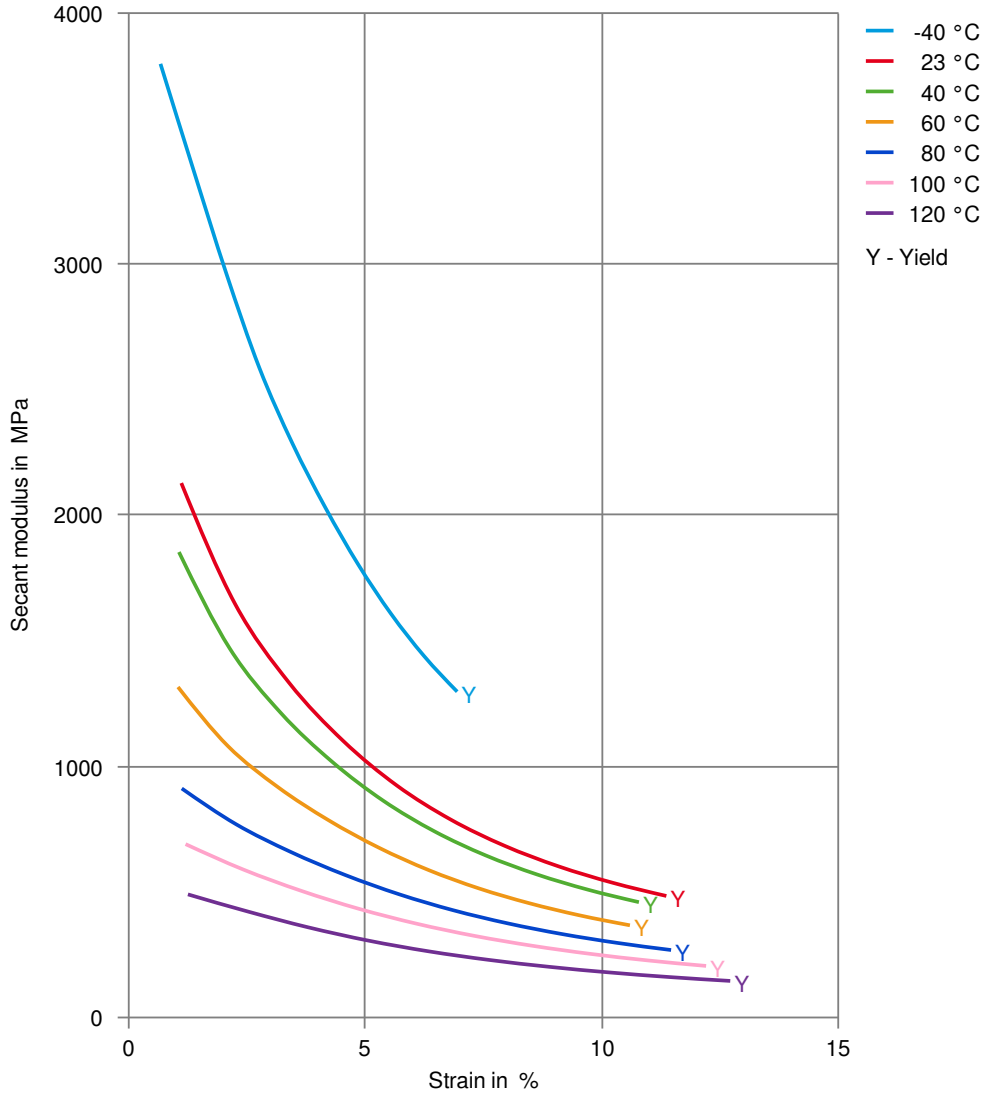
Secant modulus-strain



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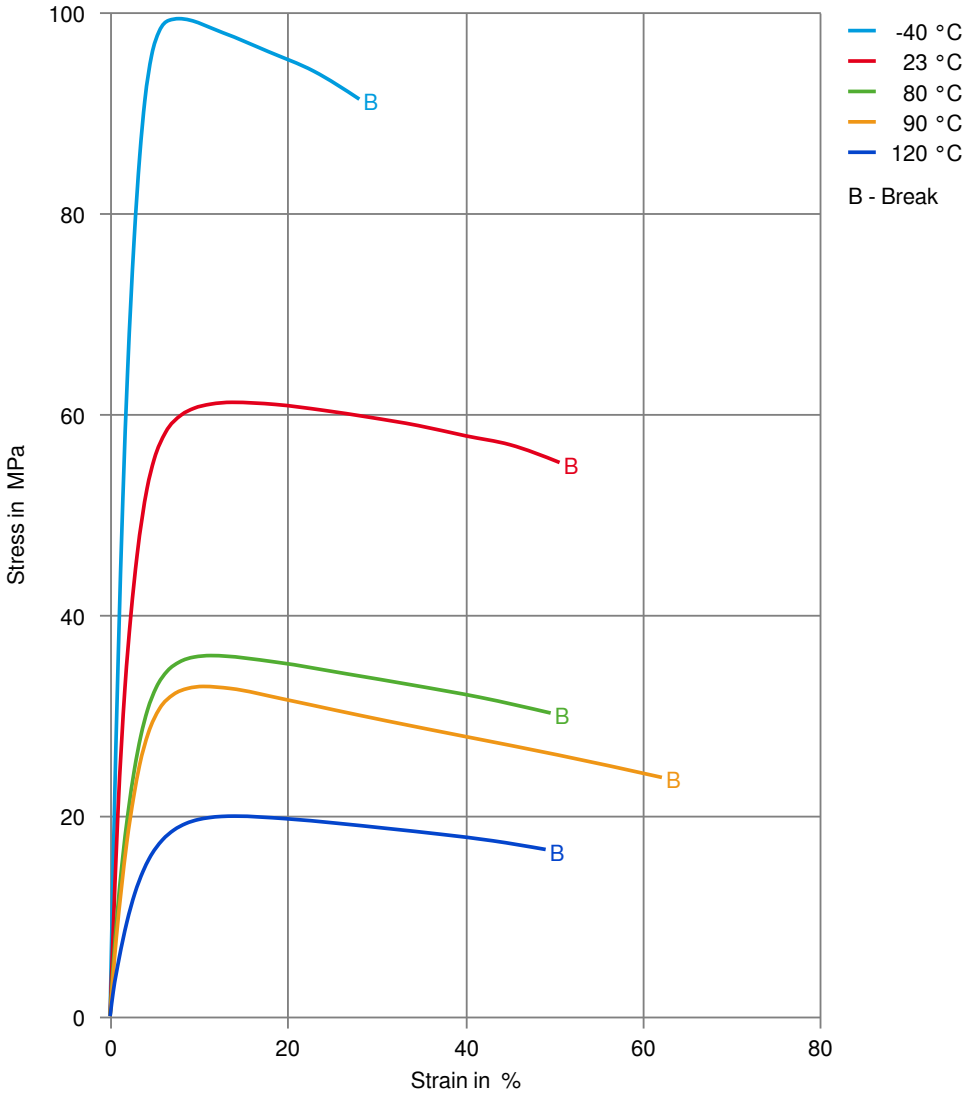
Stress-strain, 50mm/min



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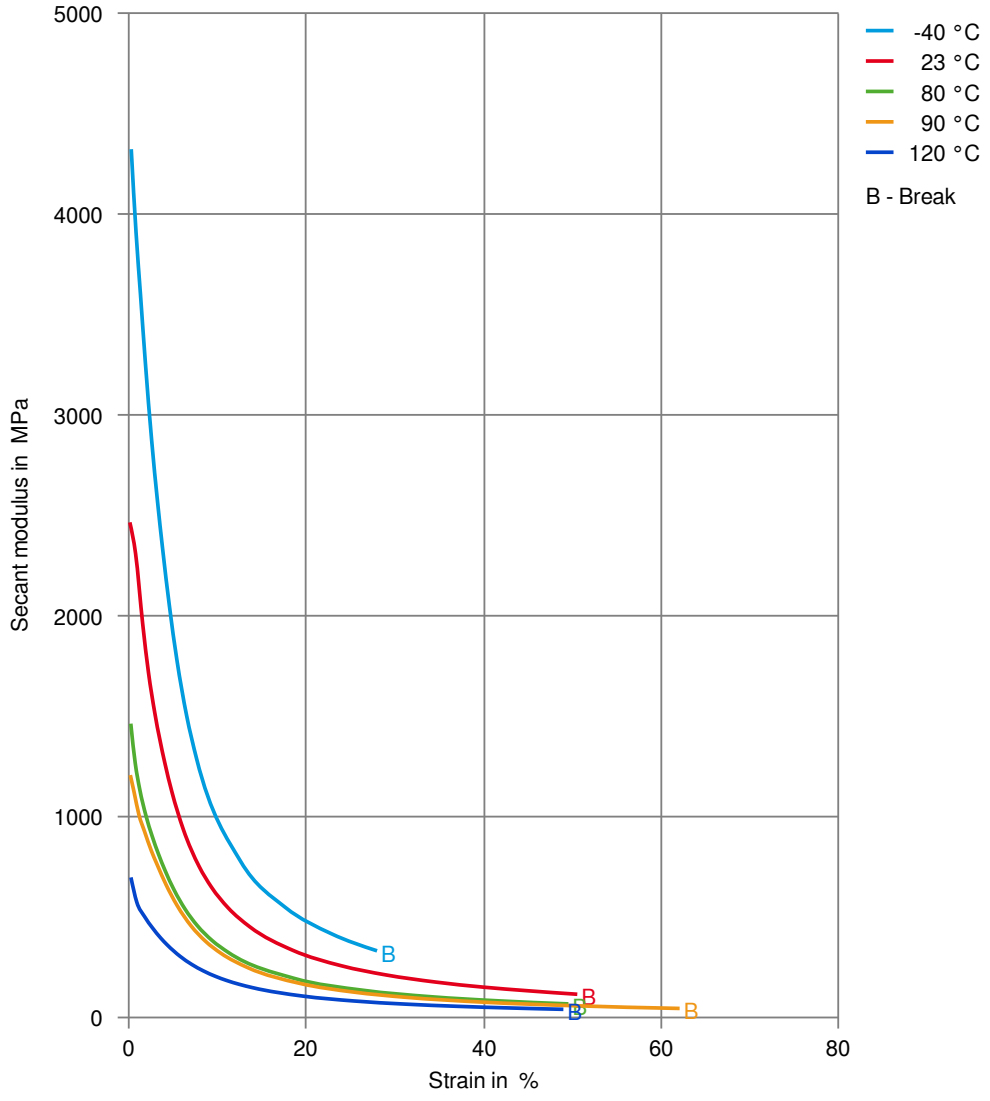
Secant modulus-strain, 50mm/min



Revised: 2025-03-05 Source: Celanese Materials Database